



# BES2700IH

Brief Datasheet

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## Ultra-low Power Bluetooth Audio Platform for TWS, Hybrid ANC and AI Voice Applications

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### CONTACT US:

**Company:** Bestechnic (Shanghai) Co., Ltd. (“BES”)

**Address:** 2F, Building B, Lane 2889 Jinke Road, Pudong, Shanghai (201203)

**Phone:** (86)21 6877 1788

For product inquiries and more information, please visit [www.bestechnic.com](http://www.bestechnic.com).

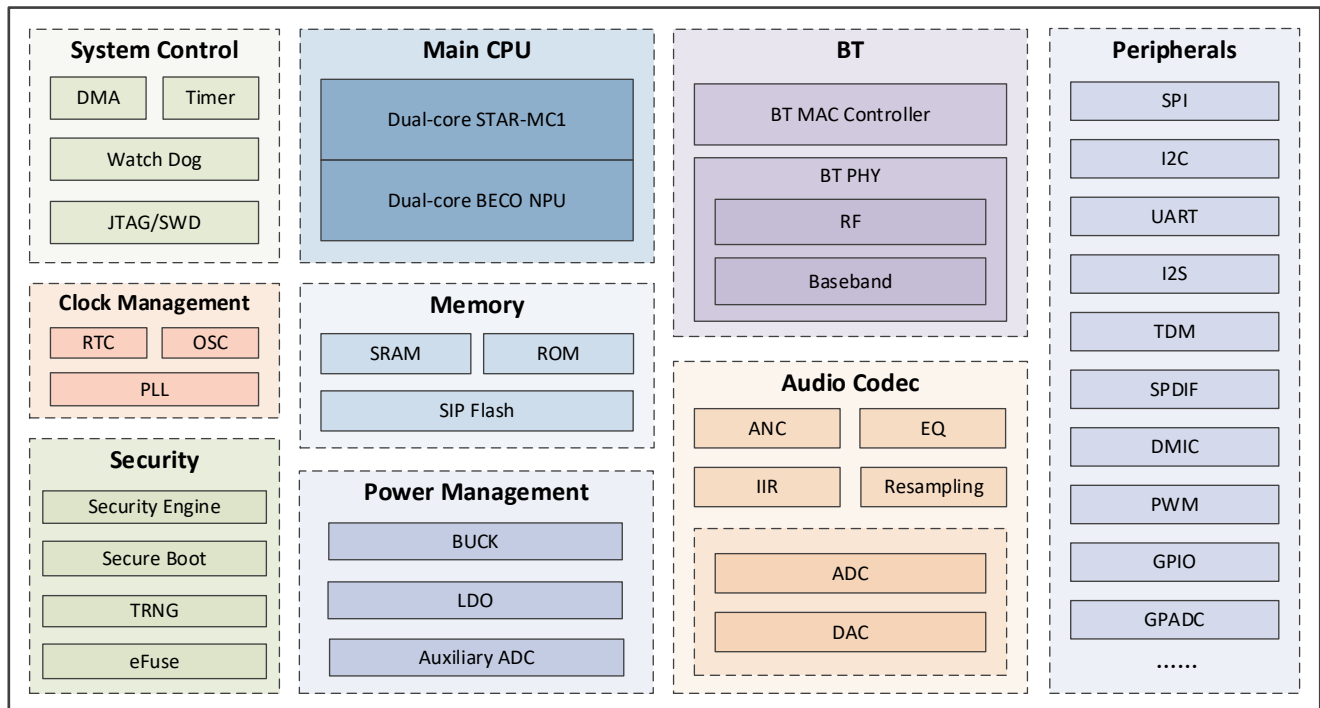
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## 1 General Description

The BES2700IH is an ultra-low power Bluetooth audio SoC that integrates a dual-mode Bluetooth 5.4 subsystem and an audio codec subsystem, a high performance CPU subsystem that includes a dual-core STAR-MC1 and a dual-core BECO NPU, a BES proprietary coprocessor for advanced signal processing and NN workloads, RAM/ROM, serial flash for software functions and product customization, and interfaces.

With its highly integrated design and extremely small package size, the BES2700IH is not only suitable for increasingly smaller TWS earbuds applications, but is also ideal for smart rings, where the BES2700IH supports ultra-low power BLE mode.



System Block Diagram

### 1.1 Applications

- Smart ANC TWS earbuds
- Smart rings
- Other wearable or portable audio devices

## 1.2 Features & Specifications\*

CPU Subsystem	Dual-core STAR-MC1
Memory and Storage	Shared 1.4 MB SRAM
	Flash in package
	boot ROM
Bluetooth Subsystem	Dual-mode BT 5.4 with LE audio
Audio & Voice Features	1x DAC
	3x ADCs
Peripheral Interfaces	SPI/I2C/UART/I2S/TDM/SPDIF/DMIC/PWM/GPIO/GPADC.....
Package	120-pin BGA

\* The content in the table is subject to change without notice.